

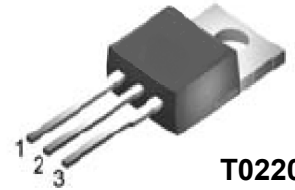
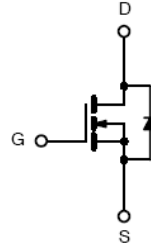


# PMG20N65P N-Channel Enhancement Mode MOSFET

Product Summary			
$I_D$	$T_A=25^\circ\text{C}$	20A	Max
$V_{(BR)DSS}$	$I_D=250\mu\text{A}$	650V	Min
$r_{DS(on)}$	$V_{GS}=10\text{V}$	0.17 $\Omega$	Typ

## Features

- Low  $r_{DS(on)}$
- Ultra Low Gate Charge
- High dV/dt capability
- High Unclamped Inductive Switching (UIS) capability
- High peak current capability
- Increased transconductance performance
- Optimized design for high performance power systems



**TO220**

Standard Metal  
Heatsink

1=Gate, 2=Drain,  
3=Source.

## Maximum Ratings and Thermal Characteristics <sup>b</sup> ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	650	V
Gate-Source Voltage (Static)	VGS	$\pm 20$	
Gate-Source Voltage AC ( $f > 1\text{Hz}$ )	VGS	$\pm 30$	
Drain Current	- Continuous ( $T_c = 25^\circ\text{C}$ )	ID	A
	- Pulsed (limited by $T_{jmax}$ )	IDM	
Repetitive Avalanche Current (limited by $T_{jmax}$ )	IAR	7	A
Energy in Avalanche (single pulse, $I_D = 3.5\text{A}$ )	EAS	690	mJ
Maximum Power Dissipation ( $T_c = 25^\circ\text{C}$ )	PD	208	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$
dV/dt voltage slope ( $V_{ds}=480\text{V}, I_D=20\text{A}, T_j = 125^\circ\text{C}$ )	dV/dt	50	V/ns
Thermal Resistance	- Junction-to-Ambient	RthJA	$^\circ\text{C/W}$
	- Junction-to-Case	RthJC	$^\circ\text{C/W}$

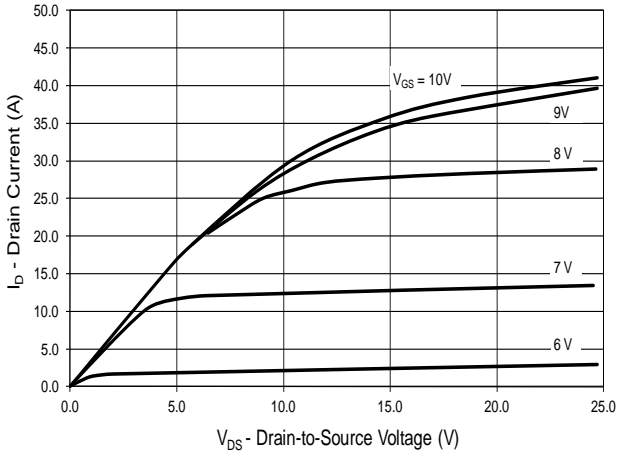
a When mounted on 1 inch square 2oz copper clad FR-4

b Preliminary Data Sheet - Specifications subject to change.

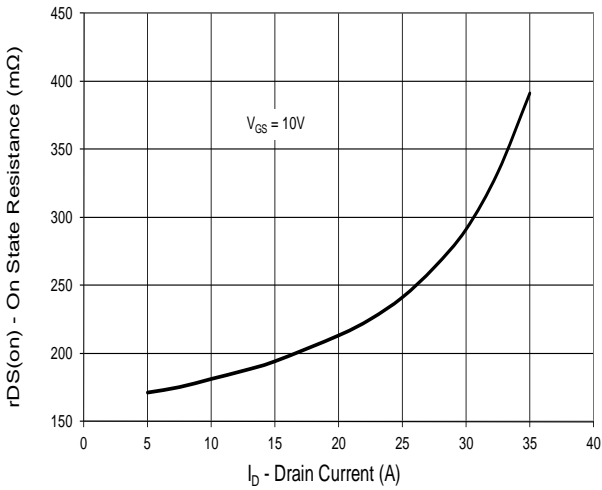
**Electrical Characteristics<sup>b</sup>** (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	650	675		V
I <sub>bss</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V T <sub>J</sub> = 150°C		0.1	1	μA
				20	100	μA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V		10	100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2.5	3	3.5	V
r <sub>DS(on)</sub>	Drain-to-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =10A T <sub>J</sub> = 150°C	0.139	0.17	0.199	Ω
			0.33	0.4	0.597	Ω
R <sub>G</sub>	Gate Resistance	f = 1MHz,	0.2	0.5	0.7	Ω
g <sub>fs</sub>	Transconductance	V <sub>DS</sub> > 2*I <sub>D</sub> *R <sub>DS</sub> , I <sub>D</sub> = 10A	13	20	30	S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	900	2400	2700	pF
C <sub>oss</sub>	Output Capacitance		600	780	820	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		20	50	70	pF
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =10V, I <sub>D</sub> =20A, V <sub>DS</sub> =380V R <sub>G</sub> = 4Ω (External)	5	10	12	nS
t <sub>r</sub>	Rise Time		2	5	7	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		30	67	100	nS
t <sub>f</sub>	Fall Time		2	4.5	12	nS
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =10V, I <sub>D</sub> =20A, V <sub>DS</sub> =480V	65	87	114	nC
Q <sub>gs</sub>	Gate-to-Source Charge		6	11	13	nC
Q <sub>gd</sub>	Gate-to-Drain Charge		23	33	36	nC
V <sub>(plateau)</sub>	Gate Plateau voltage		2	5.5	7	V
t <sub>rr</sub>	Source-to-Drain Reverse Recovery Time	I <sub>S</sub> =I <sub>F</sub> , di/dt=100A/uS, V <sub>rr</sub> =480V	100	200	250	nS
Q <sub>rr</sub>	Reverse recovery charge		7	11	14	μC
I <sub>rm</sub>	Peak reverse recovery current		30	70	80	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =I <sub>F</sub> , V <sub>GS</sub> =0V	0.5	1.0	1.2	V

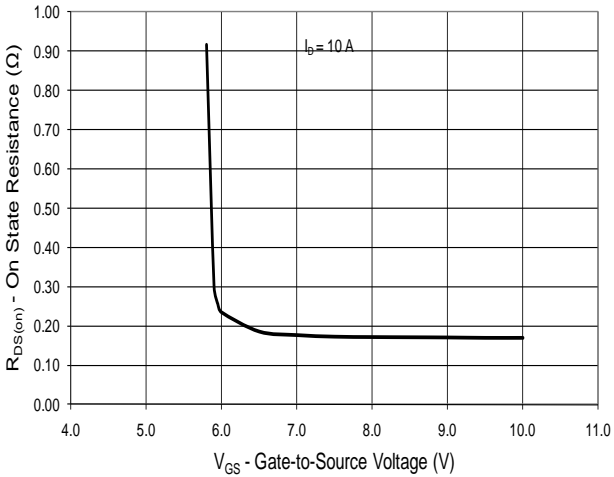
**Output Characteristics**



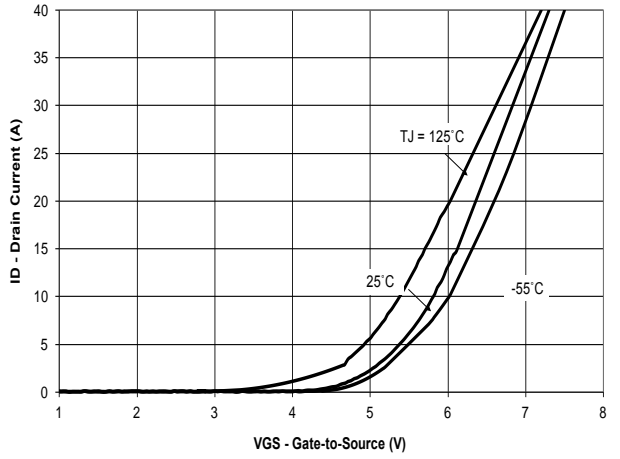
**On State Resistance vs. Drain Current**



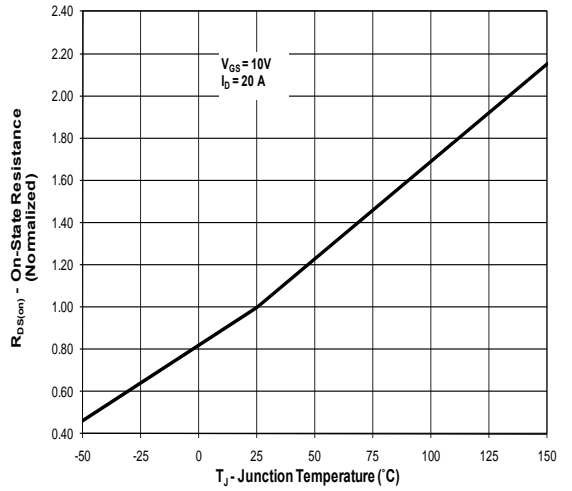
**On-Resistance vs. Gate-to-Source Voltage**



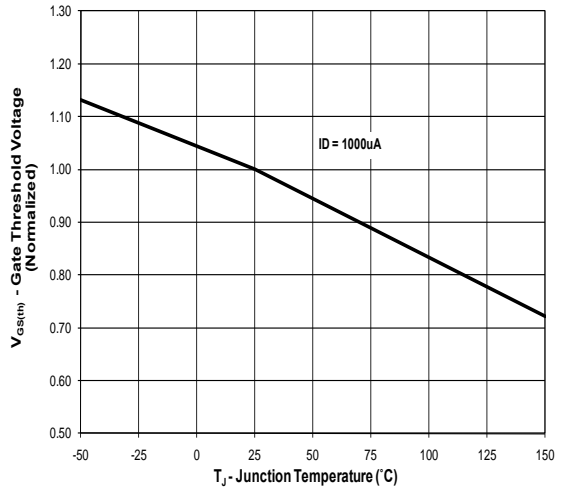
**Transfer Characteristics**



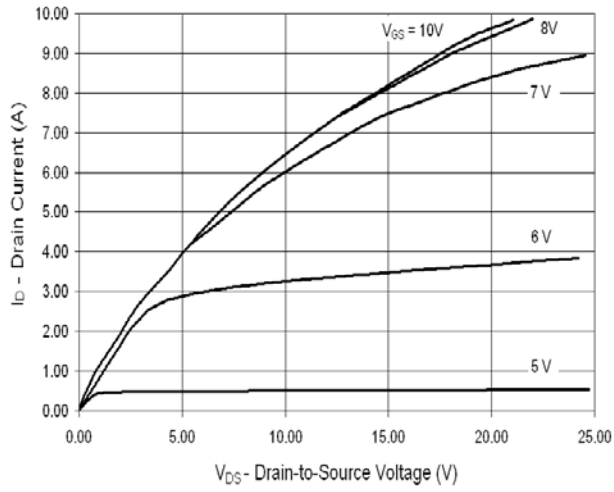
**On-State Resistance vs. Junction Temperature**



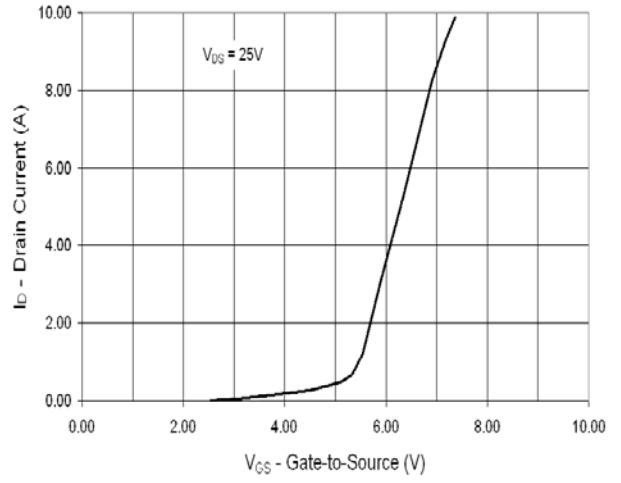
**Gate Threshold Voltage vs. Junction Temperature**



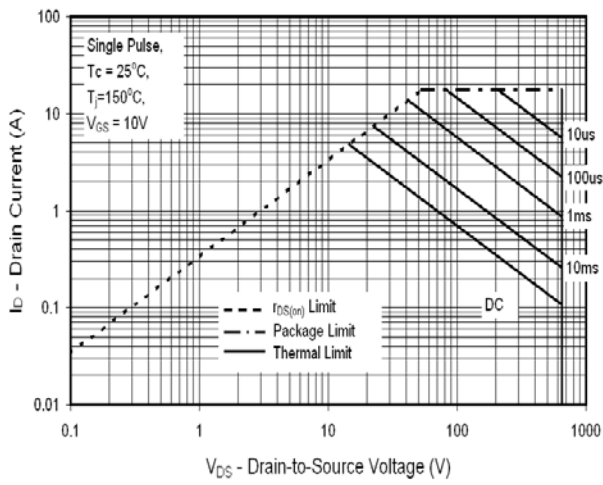
Output Characteristics



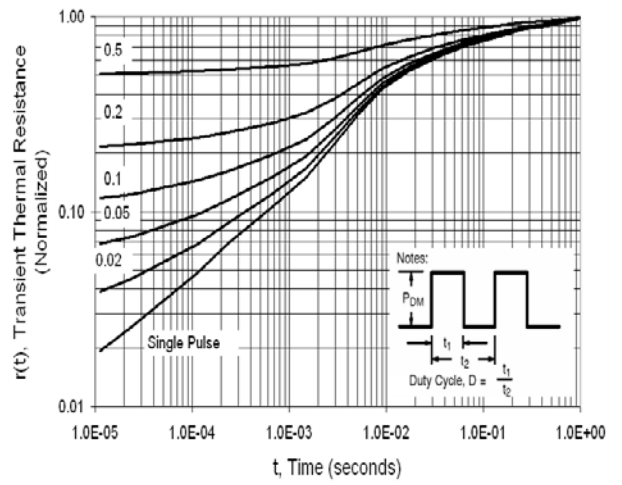
Transfer Characteristics

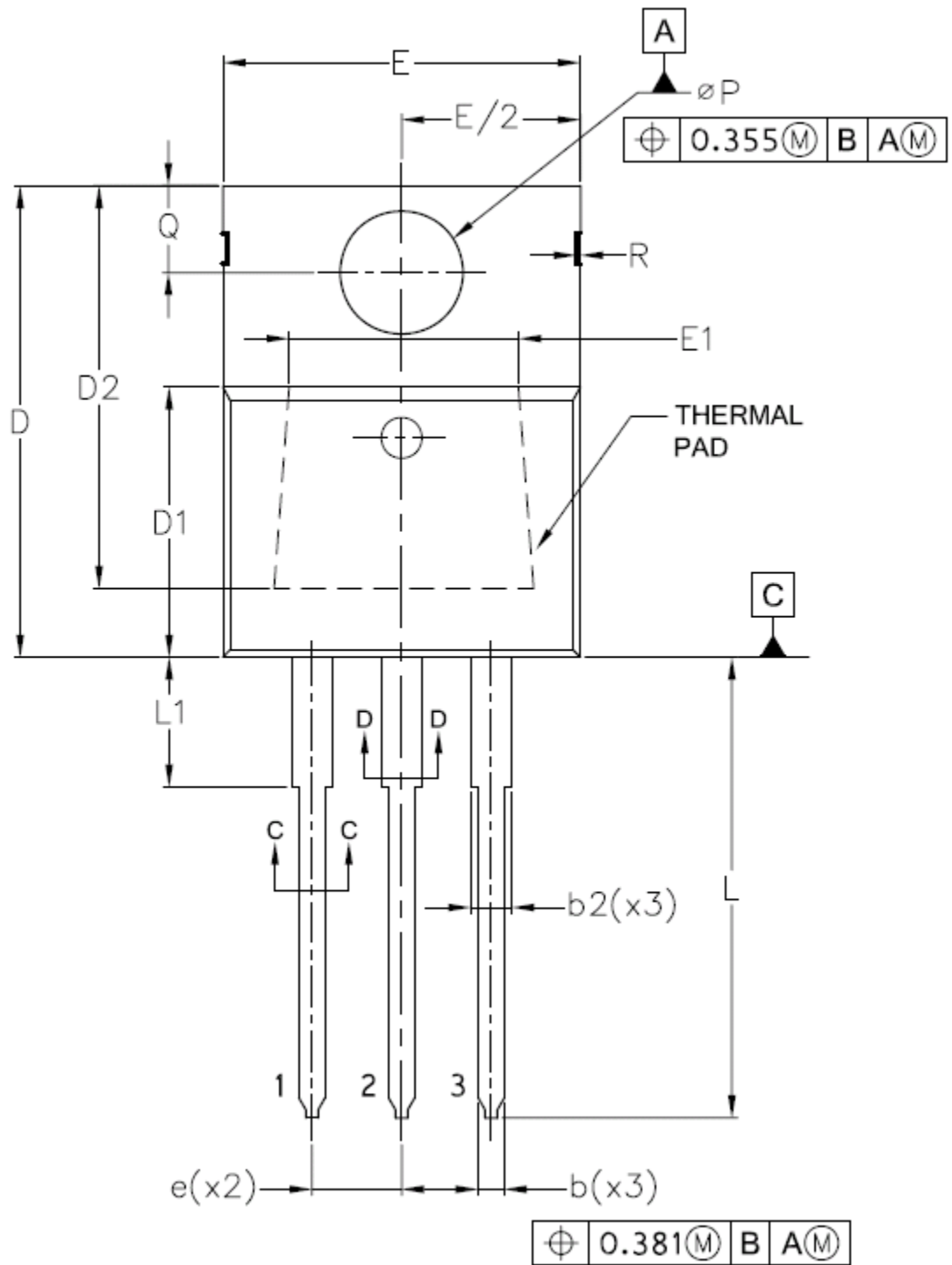


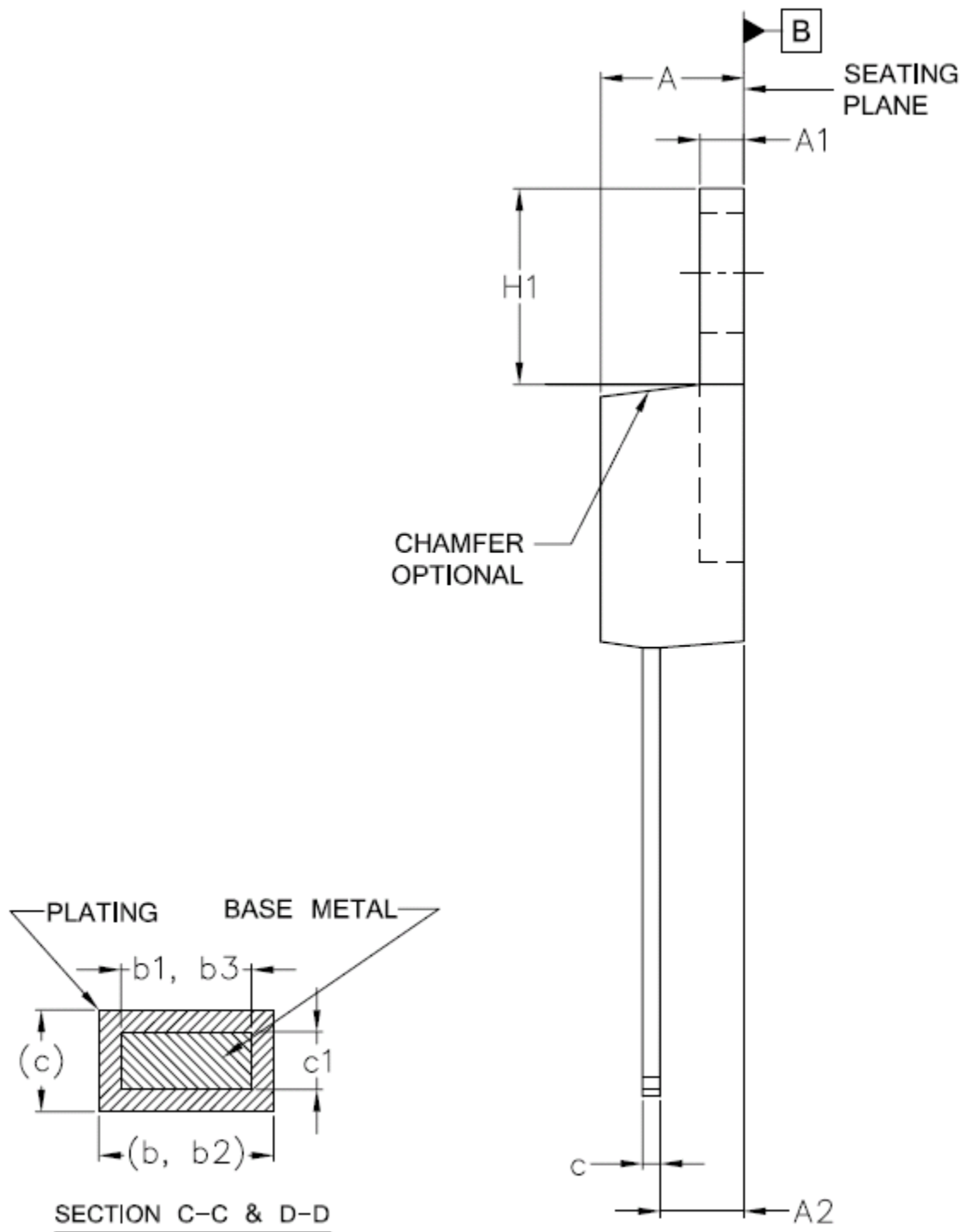
Maximum Rated Forward Biased Safe Operating Area



Transient Thermal Response, Junction-to-Case







SYMBOLS	DIMENSIONS			
	mm		Inch	
	MIN.	MAX.	MIN.	MAX.
A	3.556	4.826	0.140	0.190
A1	0.508	1.397	0.020	0.055
A2	2.032	2.921	0.080	0.115
b	0.381	1.016	0.015	0.040
b1	0.381	0.965	0.015	0.038
c	0.356	0.610	0.014	0.024
c1	0.356	0.559	0.014	0.022
D	14.224	16.510	0.560	0.650
D1	8.382	9.017	0.330	0.355
D2	12.192	12.878	0.480	0.507
E	9.652	10.668	0.380	0.420
E1	6.858	8.890	0.270	0.350
e	2.540 BSC		0.100 BSC	
H1	5.842	6.858	0.230	0.270
L	12.700	14.732	0.500	0.580
∅P	3.810	3.860	0.150	0.151
Q	2.540	3.048	0.100	0.120
b2	1.143	1.778	0.045	0.070
R	1.270 BSC		0.050 BSC	
L1	–	6.350	–	0.250
b3	1.143	1.727	0.045	0.068
f1	3.200 REF.		0.126 REF.	
f2	4.220 REF.		0.166 REF.	
j	1.750 REF.		0.069 REF.	
r	0.510 REF.		0.020 REF.	
N	TO-220-3L			